



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-01008	REV: A	SUN REV: Not In VersionControl
	TID #: TIDA-01008		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 12/14/2017 9:20:43 AM	TEXAS INSTRUMENTS	

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